

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of Khandros et al

Serial No.: 08/030,194

Filed: April 28, 1993

Semiconductor Chip Assemblies, Methods of Making Same And

Components For Same

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Group Art Unit: 3206

Examiner: S. Clark

Date: March 1, 1996

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Assistant Commissioner For Patents Washington, D.C. 20231

GROUP 2500

CERTIFICATION PURSUANT TO 37 C.F.R. §1.97(e)(2)

Sir:

For:

Pursuant to 37 C.F.R. §1.97(e)(2), undersigned counsel hereby certifies that no item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application to the above-referenced patent application. Moreover, to the knowledge of undersigned counsel, after making reasonable inquiry, no such item of information was known to any individual designated in 37 C.F.R. §1.56(c) more than three months prior to the filing of the accompanying Information Disclosure Statement.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on March, 1996.

(Signature)

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